

[FLIP CHIP PACKAGE STRUCTURE]

Abstract

A flip chip package structure comprising a chip, a substrate, at least a first bump and a plurality of second bumps is provided. The chip has a first bump-positioning region and the substrate has a second bump-positioning region. The substrate has at least a first hole and multiple second holes. The first hole and the second holes are located within the second bump-positioning region. The first hole has a depth greater than that of the second hole. The first bump is set up between the first bump-positioning region of the chip and the second bump-positioning region of the substrate. The first bump is bonded to the substrate through the first holes. The second bumps are set up between the first bump-positioning region of the chip and the second bump-positioning region of the substrate. The second bumps are bonded to the substrate through the second holes. The first bump has a volume greater than the volume of the second bump.